

Features:

- High inrush current withstanding capability
- Multilayer monolithic structure with glass ceramic body and silver fusing element
- Silver termination with nickel and pure-tin solder plating, providing excellent solderability
- Standard EIA1206/EIAJ3216 size
- Compatible with both wave and reflow soldering processes
- Operating temperature range: -55°C to +125°C (with de-rating)
- RoHS compliant

Clear-Time Characteristics (Slow Blow):

% of current rating	Clear-time at 25 °C	
100%	4 hours min.	
200%	1 second min.	120 seconds max.
300%	0.1 seconds min.	3 seconds max.
800%	0.002 seconds min.	0.05 seconds max.

Agency Approval: Recognized Under the Components Program of Underwriters Laboratories. File Number: E232989

Patents: U.S. Patent numbers 6,034,589; 6,228,230; 6,602,766; 7,268,661 B2; and other pending patents.

Interrupting Ratings:

1A - 5.5A 50A at rated voltages
6A - 8A 60A at rated voltage

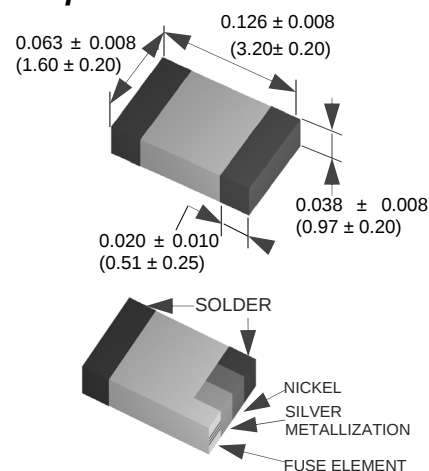
Ordering Information:

Part NO. 料号	Rated Voltage 额定电压	Rated Current 额定电流	Typical Cold Resistance (Ω) 冷电阻	Typical Pre-Arcing I ² t(A ² S) 融化热能	Marking 标示
F1206SB1000V063T	63V _{DC}	1.0A	0.360	0.11	E
F1206SB1250V063T	63V _{DC}	1.25A	0.200	0.22	F
F1206SB1500V063T	63V _{DC}	1.5A	0.150	0.23	G
F1206SB2000V063T	63V _{DC}	2.0A	0.082	0.63	I
F1206SB2500V063T	32V _{DC}	2.5A	0.070	0.90	J
F1206SB3000V063T	33V _{DC}	3.0A	0.032	1.20	K
F1206SB3500V063T	32V _{DC}	3.5A	0.028	1.60	L
F1206SB4000V063T	32V _{DC}	4.0A	0.024	2.20	M
F1206SB4500V063T	32V _{DC}	4.5A	0.020	3.60	T
F1206SB5000V063T	32V _{DC}	5.0A	0.016	5.30	N
F1206SB5500V063T	24V _{DC}	5.5A	0.014	6.40	U
F1206SB6000V063T	24V _{DC}	6.0A	0.011	8.50	O
F1206SB7000V063T	24V _{DC}	7.0A	0.010	10.0	P
F1206SB8000V063T	24V _{DC}	8.0A	0.009	16.9	R

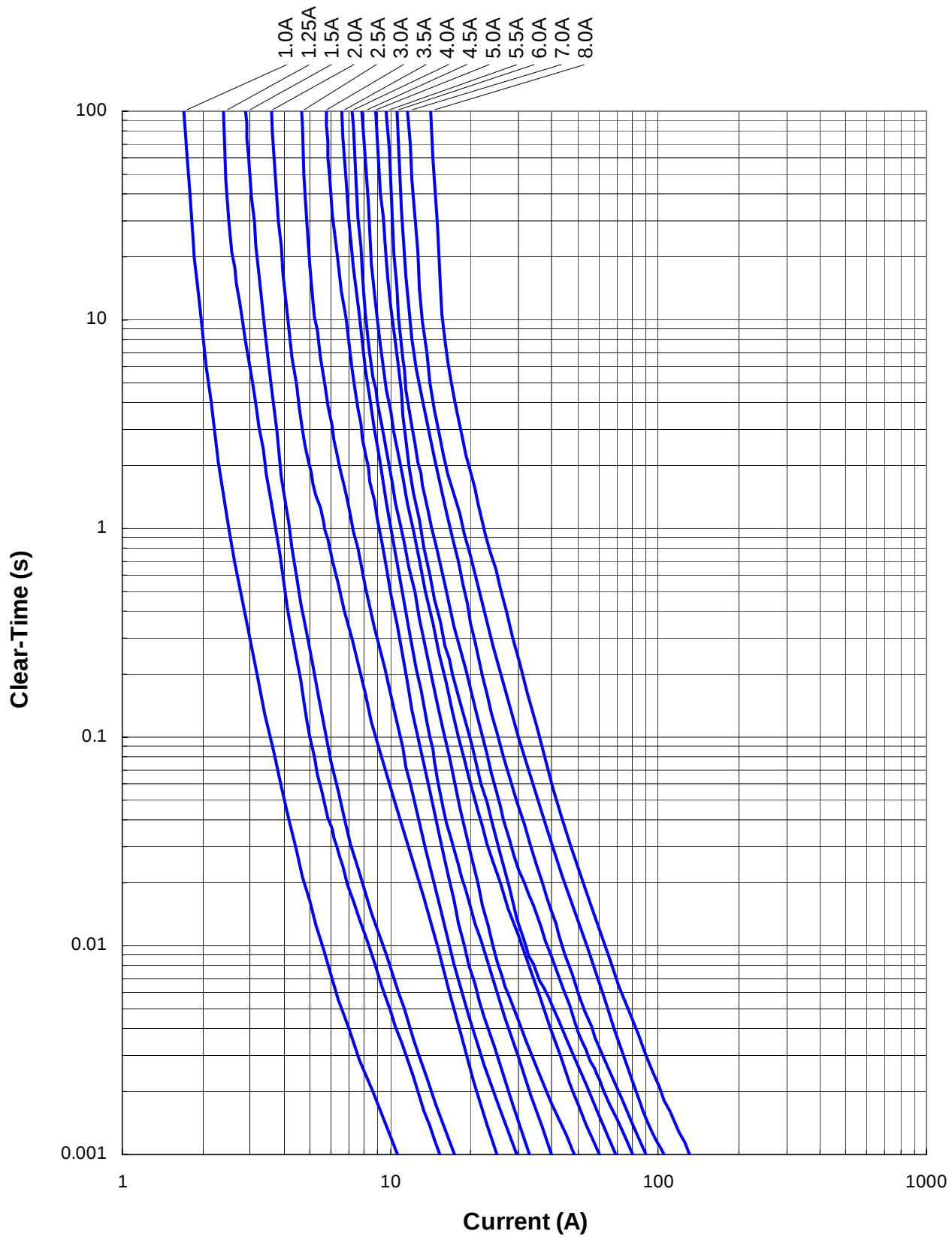
1. Measured at ≤ 10% of rated current and 25°C ambient
2. Melting I²t at 0.001 sec clear-time



Shape and Dimensions:

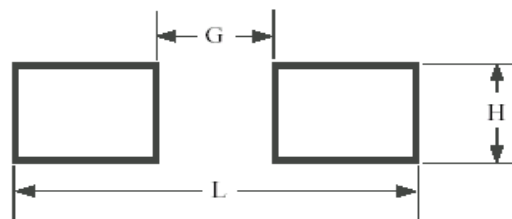


Average Clear-Time Curves



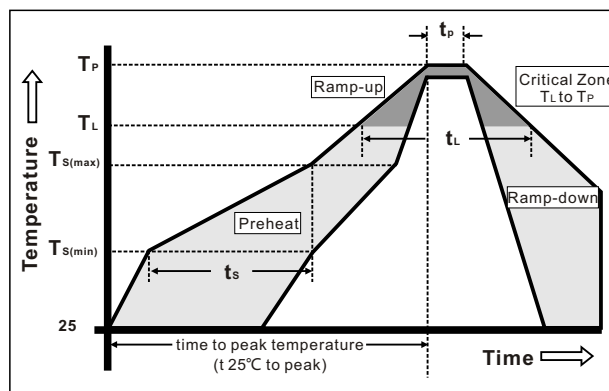
Recommended PC Board Land Pattern

Chip Size	L INCH (mm)	G INCH (mm)	H INCH (mm)
1206 (3216)	0.173 (4.40)	0.059 (1.50)	0.071 (1.80)



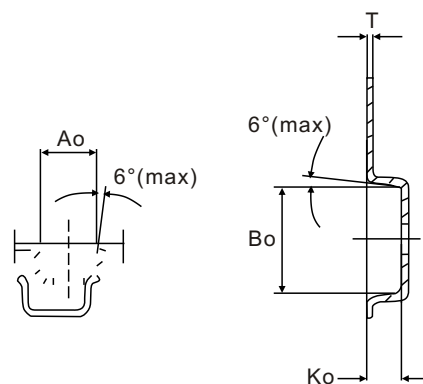
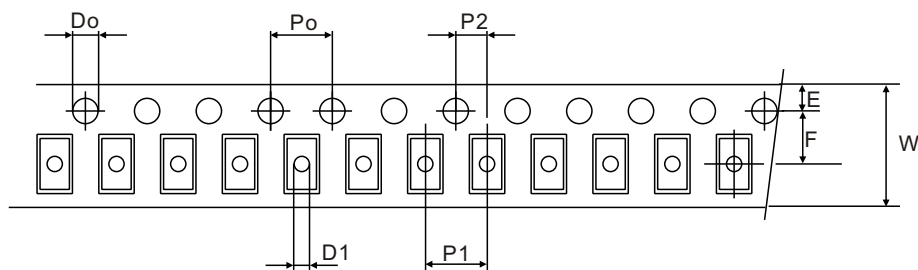
Recommended Temperature Profile for Reflow Soldering

Reflow Condition		Pb-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 - 120 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		3°C/second max.
TS(max) to TL - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 - 150 seconds
Peak Temperature (T_P)		260±0/-5°C
Time within 5° C of actual peak Temperature (t_p)		30 seconds
Ramp-down Rate		6°C/second max
Time 25° C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C



Solder Pot Temperature: 260°C max Solder Dwell Time: 10 Seconds max

Packaging dementions



Symbol	Ao	Bo	Ko	Po	P1	P2
Spec	1.80±0.10	3.50±0.10	1.27±0.10	4.00±0.10	4.00±0.10	2.00±0.10
Symbol	E	F	Do	D1	W	T
Spec	1.75±0.10	3.50±0.10	1.50±0.10	1.00(Max)	8.00±0.10	0.23±0.02

(Unit: mm)

Chip Size	Parts on 7 inch(178mm) Reel
1206(3216)	3000